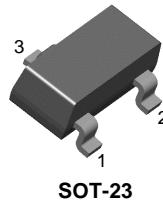
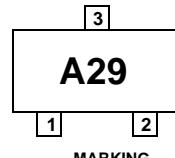


MMBD1401A / 1403A / 1404A / 1405A

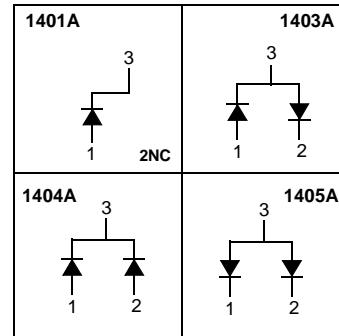


SOT-23



MARKING
MMBD1401A A29 MMBD1404A A33
MMBD1403A A32 MMBD1405A A34

Connection Diagram



High Voltage General Purpose Diode

Sourced from Process 2V.

Absolute Maximum Ratings *

T_A = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
W _{IV}	Working Inverse Voltage	175	V
I _O	Average Rectified Current	200	mA
I _F	DC Forward Current	600	mA
i _f	Recurrent Peak Forward Current	700	mA
i _{f(surge)}	Non-repetitive Peak Forward Surge Current Pulse Width = 1.0 second Pulse Width = 1.0 microsecond	1.0 2.0	A
T _{STG}	Storage Temperature Range	-55 to +150	°C
T _J	Operating Junction Temperature	150	°C

* These ratings are limiting values above which the serviceability of the diode may be impaired.

NOTES:

- 1) These ratings are based on maximum junction temperature of 150 degrees C.
- 2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations.

Thermal Characteristics

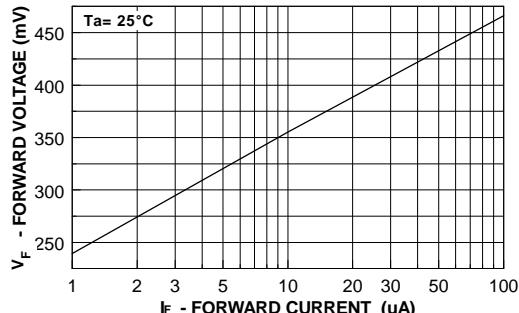
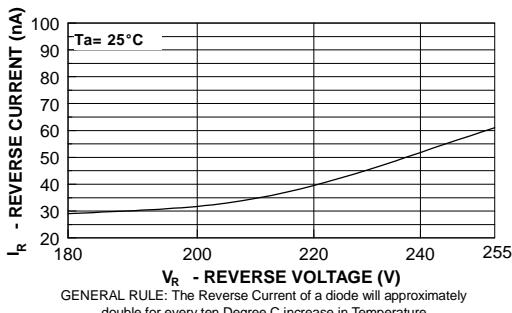
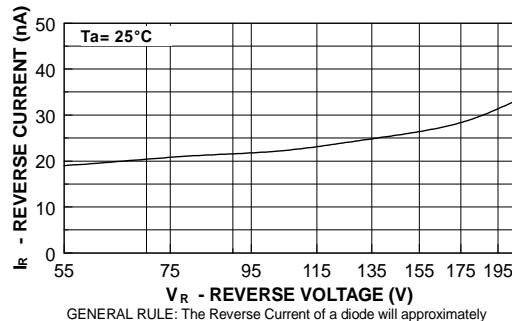
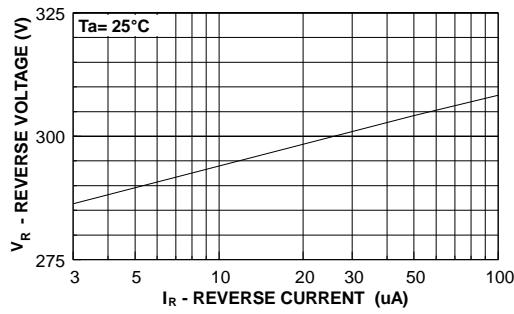
Symbol	Parameter	Max.	Units
		MMBD1401A - 1405A*	
P _D	Power Dissipation Derate above 25°C	350 2.8	mW mW/°C
R _{θJA}	Thermal Resistance, Junction to Ambient	357	°C/W

* Device mounted on glass epoxy PCB 1.6" x 1.6" x 0.06"; mounting pad for the collector lead min. 0.93 in 2

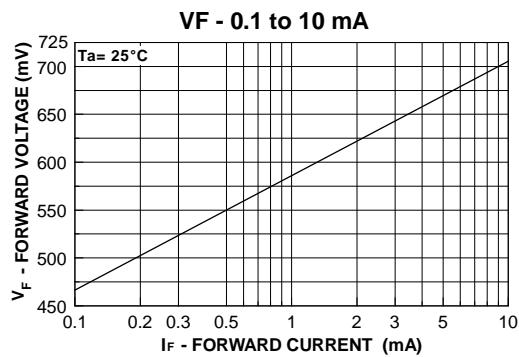
Electrical Characteristics T_A=25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Max.	Units
B _V	Breakdown Voltage	I _R = 100µA	250		V
I _R	Reverse Leakage	V _R = 120V V _R = 175V		40 100	nA nA
V _F	Forward Voltage MMBD1401A/1403A MMBD1404A/1405A MMBD1401A/1403A MMBD1404A/1405A	I _F = 10mA	760	800	mV
		I _F = 50mA		920	mV
		I _F = 200mA		1.1	V
		I _F = 200mA		1.0	V
		I _F = 300mA		1.25	V
		I _F = 300mA		1.1	V
C _O	Diode Capacitance	V _R = 0, f = 1.0MHz		2.0	pF
T _{RR}	Reverse Recovery Time	I _F = I _R = 30mA I _{RR} = 1.0mA, R _L = 100Ω		50	nS

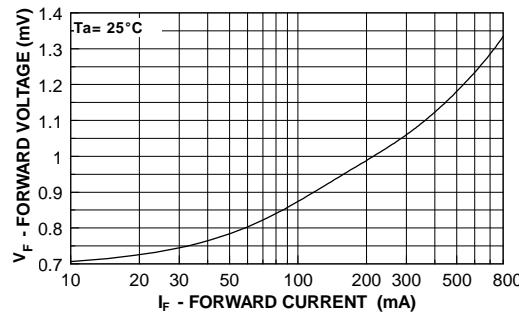
Typical Characteristics



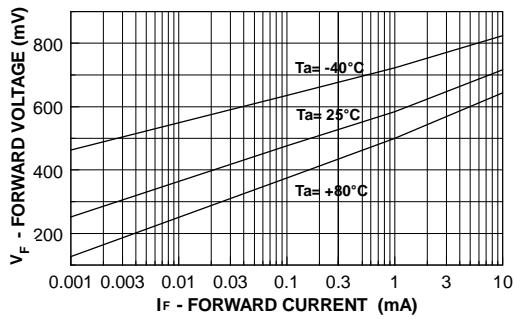
Typical Characteristics (Continued)



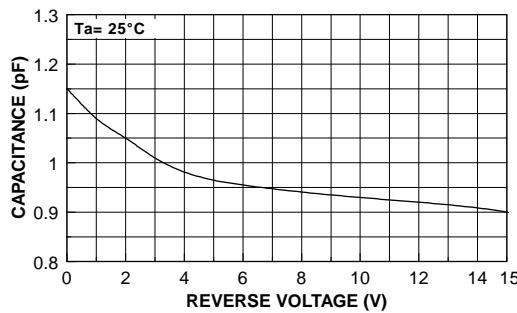
**Figure 5. Forward Voltage vs Forward Current
VF - 0.1 to 10mA**



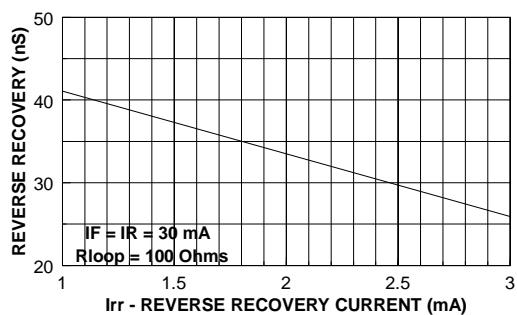
**Figure 6. Forward Voltage vs Forward Current
VF - 10 to 800mA**



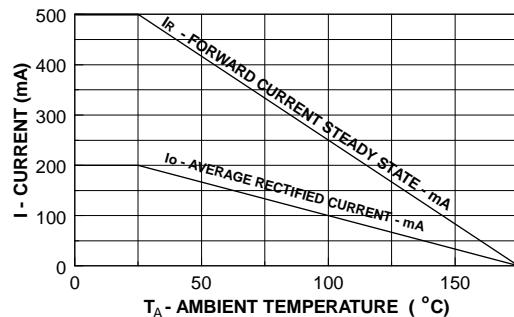
**Figure 7. Forward Voltage vs Ambient Temperature
VF - 1.0 μ A - 10mA (- 40 to +80°C)**



**Figure 8. Capacitance vs Reverse Voltage
VR - 0 to 5V**



**Figure 9. Reverse Recovery Time vs
Reverse Recovery Current (Irr)**



**Figure 10. Average Rectified Current(I_0) &
Forward Current (I_F) vs Ambient Temperature(T_A)**

Typical Characteristics (Continued)

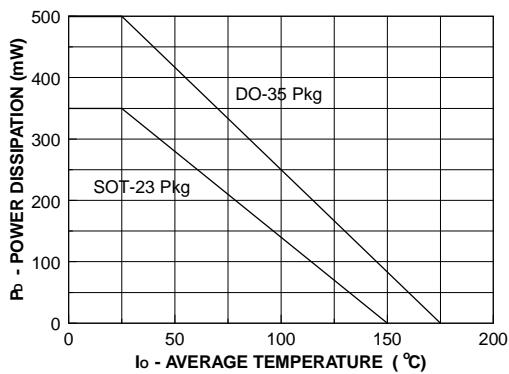


Figure 11. Power Derating Curve

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